



**IEEE
ISCAS 2023**
IEEE International Symposium on Circuits and Systems
May 21-25, 2023 || Monterey, California



CALL FOR PAPERS

IMPORTANT DATES

CALL FOR PAPERS DEADLINES

November 7, 2022

Regular Paper Submission

January 20, 2022

Author Notification

February 4, 2023

Final Manuscript Submission



TOPICS OF INTEREST

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems (CAS) Society and the world's premiere forum for researchers in the active fields of theory, design and implementation of circuits and systems. This is accomplished through technical conference sessions, poster sessions, live demonstration sessions, and publication of conference papers. ISCAS 2023 will be driven by the theme "Technology Disruption and Society" aiming to emphasize the potential of the CAS Society to find innovative solutions to challenges facing society today.

Unless conditions change substantially over the coming year, ISCAS 2023 will be an in-person event and authors are expected to be onsite to present their papers.

This year's meeting will highlight the following innovation themes:

- » Artificial Intelligence & Deep Learning
- » Big Data Processing
- » Internet of Things
- » Distributed and Decentralized Systems
- » Intelligent Video Analytics and Vision Systems
- » Zettabyte Communication Infrastructure
- » Storage Class Memories and Computational Storage
- » Personalized Healthcare Systems
- » Brain: Innovative NeuroTechnologies
- » Disaster and Pandemic Prevention and Mitigation
- » Green and Sustainable Computing and Systems
- » Technologies for Responsible, Fair and Ethical IT

Collecting contributions in all areas of Circuits and Systems, including but not limited to:

- » Analog and Mixed Signal Circuits and Systems
- » Digital Integrated Circuits and Systems
- » Power and Energy Circuits and Systems
- » Sensory Circuits and Systems
- » Nonlinear Systems and Circuit Theory
- » Digital Signal Processing
- » Multimedia Systems and Applications
- » Communications Circuits and Systems
- » Biomedical Circuits and Systems
- » Neural Networks and Neuromorphic Engineering
- » Beyond CMOS: Nanoelectronics and Heterogeneous System Integration
- » Education in Circuits and Systems

Paper Submission

Selected papers will be invited for possible publication either in the IEEE Transaction on Circuits and Systems – Part I, in the IEEE Transaction on Circuits and Systems – Part II, or in the IEEE Transaction on Biomedical Circuits and Systems.

About Monterey

Picture seaside cliffs and pristine beaches, where you might spot whales, sea otters and migrating birds. From famous writers' haunts to Spanish Missions, the history here is just as fascinating as the geography. Aside from the epic scenery, you'll savor unforgettable flavors from the area's award-winning food and wine scene. Plus, there are limitless opportunities for recreation, including world-class golf, shopping, kayaking, hiking and only 70 miles from Silicon Valley.

Please visit: iscas2023.org

ORGANIZING COMMITTEE

GENERAL CHAIRS

Jan Rabaey
UC Berkeley, USA

Boris Murmann
Stanford University, USA

TPC CHAIR

Kiran Gunnam
Western Digital, USA

Massimo Alioto
NUS, Singapore

PAST TPC CHAIR (AUSTIN 2022)

Jose Silva-Martinez
Texas A&M University, USA

PLENARY

Sandro Carrara
EPFL, Switzerland

David Cumming
University of Glasgow, UK

Andrei Vladimirescu
UC Berkeley, USA and TU Delft, NL

SPECIAL SESSIONS

Eduard Alarcon
Polytechnic University of Catalonia, Spain

Hadi Heidari,
University of Glasgow, UK

TUTORIALS

Farshad Moradi
Aarhus University, Denmark

Pedram Mohseni
Case Western University, USA

Jeff Weldon
University of Hawaii, USA

DEMO

Jennifer Blain Christen
Arizona State University, USA

Daniela de Venuto
Politecnico di Bari, Italy

FINANCE

Baris Taskin
Drexel University PA, USA

Ioannis Savidis
Drexel University, PA, USA

PUBLICITY

Qiang Li
UESTC, China

Pantelis Georgiou
Imperial College London, UK

PUBLICATION

Aldo Pena Perez
Stanford University, USA

Edoardo Bonizzoni
University of Pavia, Italy

SOCIAL MEDIA & YOUNG PROF.

Jennifer Blain Christen
Arizona State University, USA

WICAS

Giulia Di Capua
University of Cassino and Southern Lazio, IT

Laura Galindez Olascoaga
UC Berkeley, USA

LOCAL ARRANGEMENTS

Mohammad (Vahid) Vahid Far
Apple, USA

Hans Spanjaart
Intel, USA

Marcelo Siero
UC Santa Cruz, USA

INDUSTRIAL CO-CHAIR

Preet Yadav
NXP Semiconductors, India

Dr. Sim Narasimha
Intel, USA

AWARDS CHAIR

Dave Allstott
Oregon State University, USA